



ADS52J90 10-Bit, 12-Bit, 14-Bit, Multichannel, Low-Power, High-Speed ADC

1 Features

- 16-Channel ADC Configurable to Convert 8, 16, or 32 Inputs
- 10-, 12-, and 14-Bit Resolution Modes
- Maximum ADC Conversion Rate:
 - 100 MSPS in 10-Bit Mode
 - 80 MSPS in 12-Bit Mode
 - 65 MSPS in 14-Bit Mode
- 16 ADCs Configurable to Convert:
 - 8 Inputs with a Sampling Rate of a 2X ADC Conversion Rate
 - 16 Inputs with a Sampling Rate of a 1X ADC Conversion Rate
 - 32 Inputs with a Sampling Rate of a 0.5X ADC Conversion Rate
- LVDS Outputs with 16X, 14X, 12X, and 10X Serialization
- Supplies: 1.2 V, 1.8 V
- 2- V_{PP} Differential Input, 0.8-V Common-Mode
- Differential or Single-Ended Input Clock
- Signal-to-Noise Ratio (SNR):
 - 61 dBFS in 10-Bit Mode
 - 70 dBFS in 12-Bit Mode
 - 73.5 dBFS in 14-Bit Mode
- Power at 100 MSPS: 41 mW/Channel
- Package: NFBGA-198 (9 mm × 15 mm)
- Pb-Free (RoHS Compliant) and Green

2 Applications

- Ultrasound Imaging
- Portable Instrumentation
- SONAR and RADAR
- High-Speed Multichannel Data Acquisition

3 Description

The ADS52J90 is a low-power, high-performance, 16-channel, analog-to-digital converter (ADC). The conversion rate of each ADC goes up to a maximum of 100 MSPS in 10-bit mode. The maximum conversion rate reduces when the ADC resolution is set to a higher value.

The device can be configured to accept 8, 16, or 32 inputs. In 32-input mode, each ADC alternately samples and converts two different inputs each at an effective sampling rate that is half of the ADC conversion rate. In 8-bit input mode, two ADCs convert the same input in an interleaved manner, resulting in an effective sampling rate that is twice the ADC conversion rate. The ADC is designed to scale its power with the conversion rate.

The ADC outputs are serialized and output through a low-voltage differential signaling (LVDS) interface along with a frame clock and a high-speed bit clock.

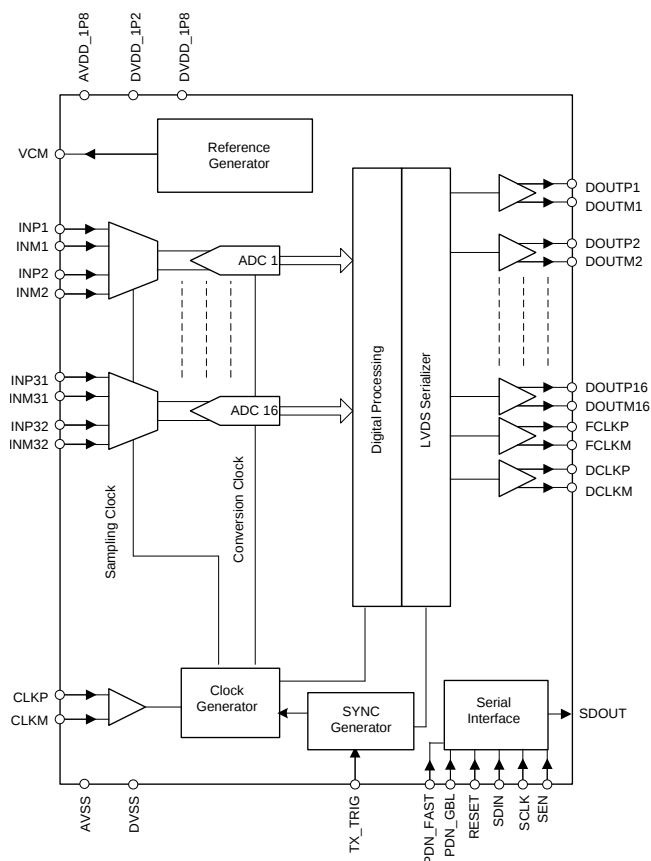
The ADS52J90 is available in a 9-mm × 15-mm, 0.8-mm pitch, NFBGA-198 package and is specified over a temperature range of –40°C to +85°C.

Device Information

PART NUMBER	PACKAGE	BODY SIZE (NOM)
ADS52J90	NFBGA (198)	9.00 mm × 15.00 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

Simplified Schematic



4 Revision History

Changes from Original (May 2015) to Revision A

Page

- Released to production [1](#)

5 Device and Documentation Support

5.1 Documentation Support

5.1.1 Related Documentation

CDCE72010 Data Sheet, [SCAS858](#)

CDCM7005 Data Sheet, [SCAS793](#)

LMK048X Data Sheet, [SNAS605](#)

SN74AUP1T04 Data Sheet, [SCES800](#)

Clocking High-Speed Data Converters, [SLYT075](#)

5.2 Trademarks

All trademarks are the property of their respective owners.

5.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

5.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

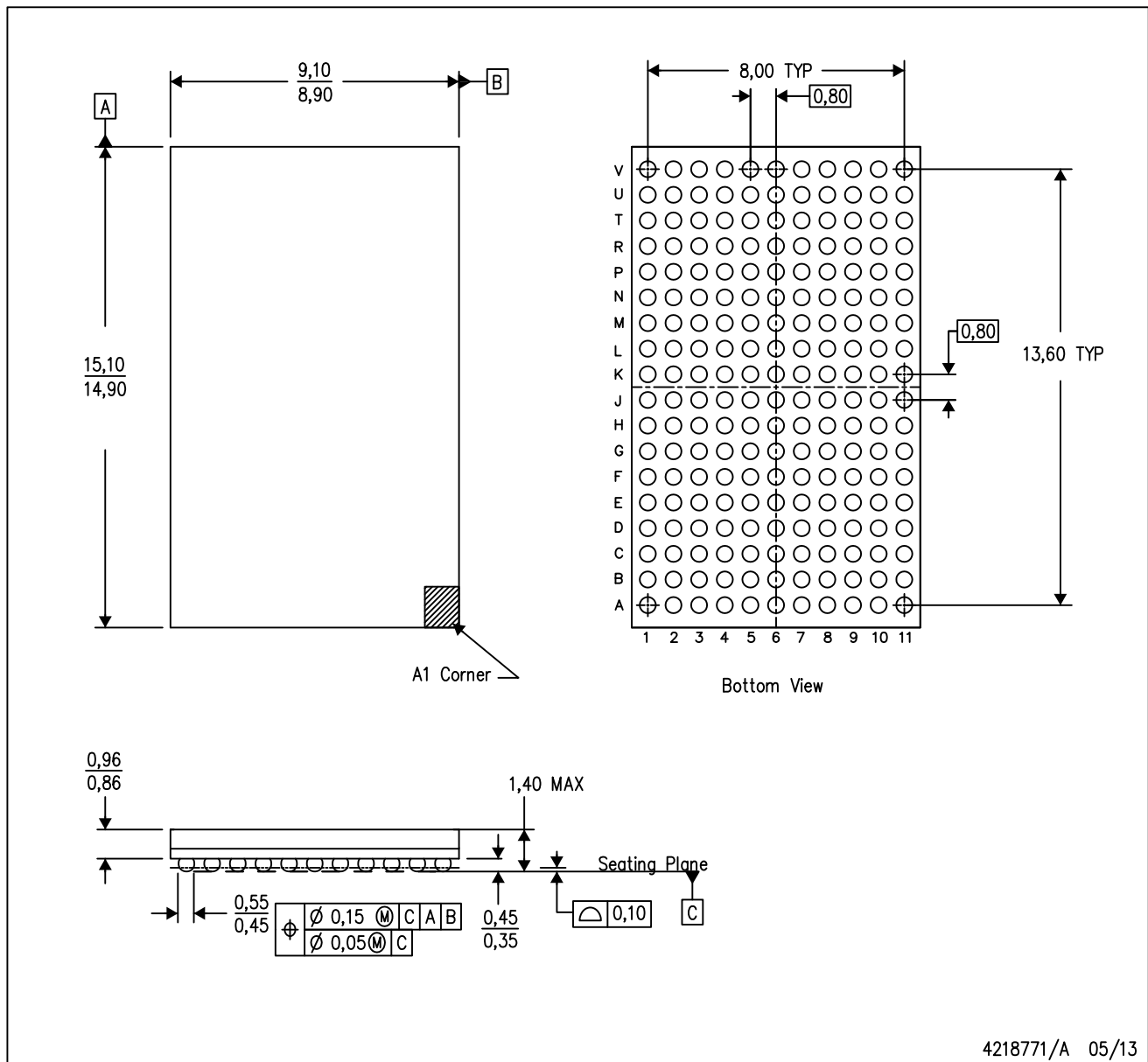
6 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

MECHANICAL DATA

ZZE (R-PBGA-N198)

PLASTIC BALL GRID ARRAY



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
 - This drawing is subject to change without notice.
 - This is a Pb-free solder ball design.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
ADS52J90ZZE	Active	Production	NFBGA (ZZE) 198	160 JEDEC TRAY (5+1)	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	ADS52J90
ADS52J90ZZE.A	Active	Production	NFBGA (ZZE) 198	160 JEDEC TRAY (5+1)	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	ADS52J90

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

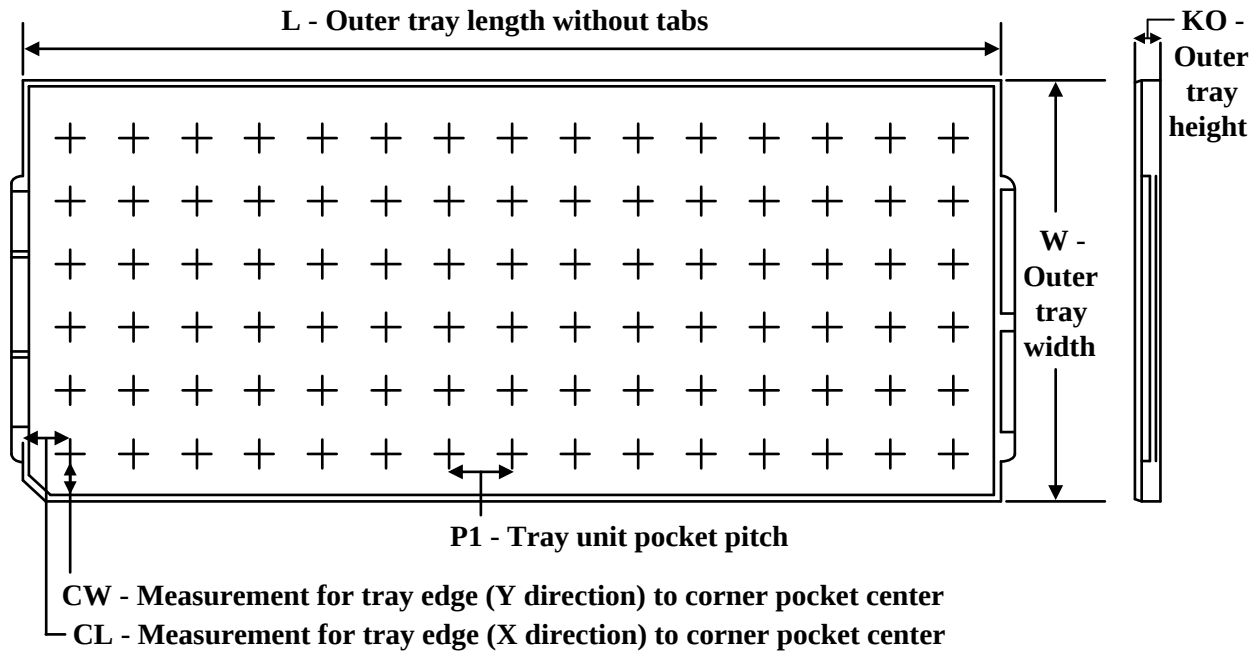
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TRAY



Chamfer on Tray corner indicates Pin 1 orientation of packed units.

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (µm)	P1 (mm)	CL (mm)	CW (mm)
ADS52J90ZZE	ZZE	NFBGA	198	160	10 x 16	150	315	135.9	7620	19.2	13.5	10.35
ADS52J90ZZE.A	ZZE	NFBGA	198	160	10 x 16	150	315	135.9	7620	19.2	13.5	10.35

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on [ti.com](#) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2026, Texas Instruments Incorporated

Last updated 10/2025